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~~said alloy having a first layer parallel to and adjacent to said backing metal, and a second layer that is not directly adjacent to said backing metal;~~

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~~wherein said roughened surface is coated with a coating layer comprising at least one thermosetting resin, which is selected from the group consisting of polyimide resin, polyamide-imide resin, epoxy resin and phenol resin, and which contains from 55 to 95% by weight of MoS₂, and wherein said roughened surface is formed of grooves extending in the sliding direction;~~

~~wherein Ag and Sn are solid-dissolved the copper alloy in at least the area adjacent said roughened surface, where essentially no secondary phase of either Ag or Sn or both is formed; and,~~

~~wherein said second layer contains a second-layer component consisting of one of:~~

~~solid-dissolved Ag and Sn,~~

~~a hexagonal compound of solid-dissolved Ag and Sn,~~


~~a hexagonal compound of Cu and solid-dissolved Ag and Sn,~~


~~a eutectic of solid-dissolved Ag and Sn, or~~

~~a eutectic of Cu and solid-dissolved Ag and Sn;~~

~~in higher concentration of Ag and Sn than that of said first layer.~~

2. (Three Times Amended) A sliding bearing for supporting an opposing shaft movable in a sliding direction against said sliding bearing, said sliding bearing consisting essentially of a copper alloy containing from 0.1 to 2% by weight of Ag, from 1 to 10% by weight of Sn, and 10% by weight

 or less of at least one additive element selected from the group consisting of Sb, In, Al, Mg and Cd,
the balance of the alloy consisting essentially of Cu,

 said alloy bonded to a backing metal and having on its side opposite to the backing metal a
roughened surface of approximately 0.5 to approximately 10 μm of roughness (R_z); and

said alloy having a first layer parallel to and adjacent to said backing metal, and a second
layer that is not directly adjacent to said backing metal;

wherein said roughened surface is coated with a coating layer comprising at least one thermo-
setting resin, which is selected from the group consisting of polyimide resin, polyamide-imide resin,
epoxy resin and phenol resin, and which contains from 55 to 95% by weight of MoS_2 , and wherein
said roughened surface is formed of grooves extending in the sliding direction;

wherein said Ag and Sn and said at least one additive element are solid-dissolved in the Cu
matrix of the copper alloy in at least the area adjacent said roughened surface, where essentially no
secondary phase of Ag or Sn or said additive element, or a secondary phase of any combination of
these, is formed;

and

wherein said second layer contains a component consisting of:

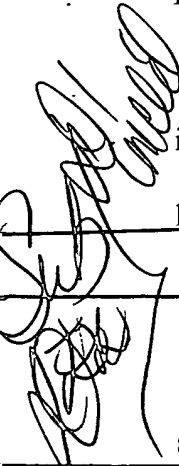
solid-dissolved Ag and Sn and said additive element,

a hexagonal compound of solid-dissolved Ag and Sn and said additive element,


a hexagonal compound of solid-dissolved Cu and Ag and Sn and said additive


element,

a eutectic of solid-dissolved Ag and Sn and said additive element, or

 a eutectic of Cu and solid-dissolved Ag and Sn and said additive element;
in higher total atomic concentration of Ag and Sn and said additive element than that of said first layer.

4. (Three times Amended) A sliding bearing according to claim 1, wherein said roughened surface is further roughened by shot-blasting, etching, flame-spraying or chemical treatment.

 9. (Two times amended) A sliding bearing according to claim 2, wherein said roughened surface is further roughened by shot-blasting, etching, flame-spraying or chemical treatment.

 11. (Amended) A sliding bearing according to claim 1, wherein the concentration of Ag and Sn in said second layer of said second-layer component is at least 1.3 times higher than that of said first layer.

12. (Amended) A sliding bearing according to claim 2, wherein the concentration of Ag and Sn in said second layer of said second-layer component is at least 1.3 times higher than that of said first layer.